PN - JP2002164257 A 20020607
PD - 2002-06-07
PR - JP20000356995 20001124
OPD - 2000-11-24
TI - LAMINATED CERAMIC ELECTRONIC COMPONENT
IN - AIBA TAKASHI;KUME HISASHI;OKABE MASAYUKI;YOSHII AKITOSHI
PA - TDK CORP
IC - H01G4/30 ; H01G4/12

TI - Laminated ceramic electronic component e.g. capacitor has nickel plated layer of specific thickness formed by electrodeposition plating in external terminal electrode
PR - JP20000356995 20001124
PN - JP2002164257 A 20020607 DW200256 H01G4/30 004pp
PA - (DENK) TDK CORP
IC - H01G4/12 ;H01G4/30
AB - JP2002164257 NOVELTY - The thickness of nickel plated layer (5b) of the external terminal electrode (5), formed by electrodeposition plating is set to 0.1-1.0 mu m.
- USE - Laminated ceramic electronic components such as ceramic capacitor, varistor, dielectric resonator and piezoelectric element for electronic device.
- ADVANTAGE - Excels in reliability, bending strength and heat resistance property.
- DESCRIPTION OF DRAWING(S) - The figure shows an expanded sectional view of the laminated ceramic electronic component. (Drawing includes non-English language text).
- External terminal electrode 5
- Nickel plated layer 5b
- (Dwg.1/3)
OPD - 2000-11-24
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TI - LAMINATED CERAMIC ELECTRONIC COMPONENT

AB - PROBLEM TO BE SOLVED: To provide a satisfactorily reliable laminated ceramic electronic component having superior flexture strength and heatcycle resistance.

- SOLUTION: The laminated ceramic electronic component is formed with its external terminal electrode laminated by a first electrode layer 5a of a base electrode layer of Ag-Pd or Cu, a second electrode layer 5b of electrolytic plated layer on the first electrode layer 5a, and a third electrode layer 5c of Sn or Sn-Pb plated layer on both ends of a laminated ceramic element4, including an internal electrode 3 therein in this order and the electrolytic Ni plated layer, is formed with its thickness in a range of0.1 to 1.0 &mu m.

I - H01G4/30 ;H01G4/12